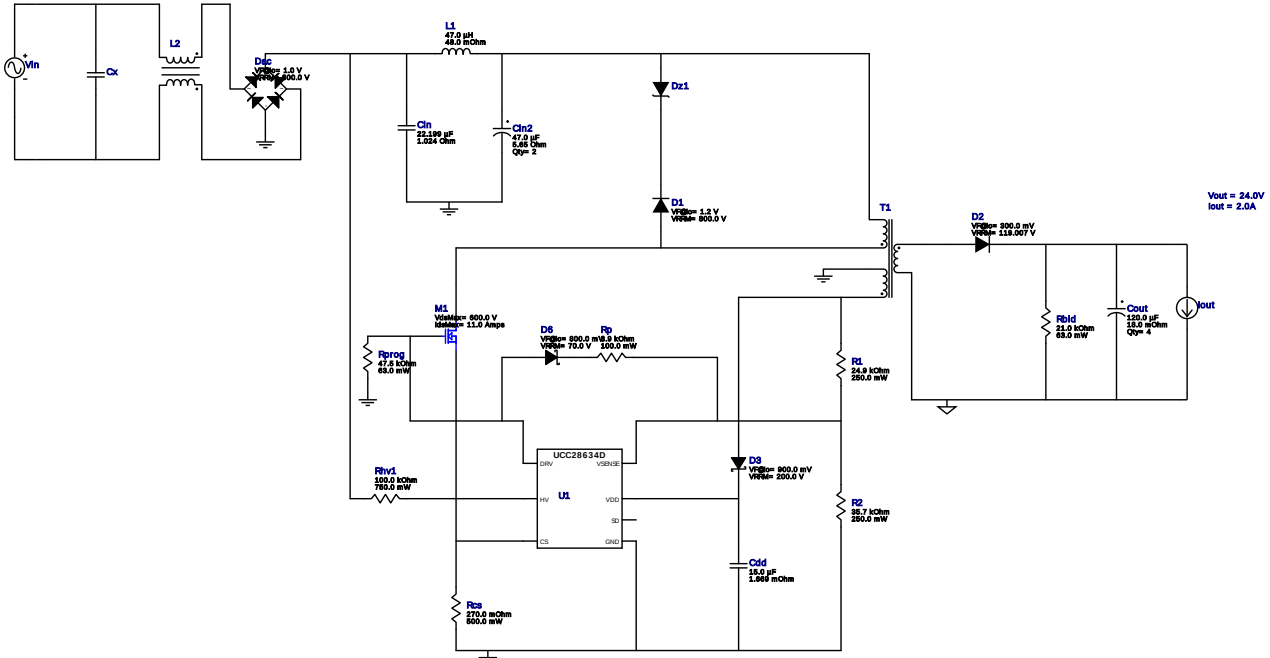


WEBENCH® Design Report

Design : 10 UCC28634DR
UCC28634DR 85V-280V to 24.00V @ 2A



1. Rbld is a starting point, but may need to be experimented with in order to get minimum current needed to hold Vout at no load. For more information please click the design assistance button.
2. Device operates in peak power region. So user needs to ensure the safe operation of 'D2' diode by using Heat sink if required.
3. Click on the transformer symbol and select 'Design Transformer' to design using specific transformer cores and bobbin

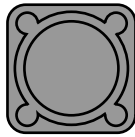
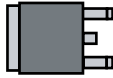
Design Alerts

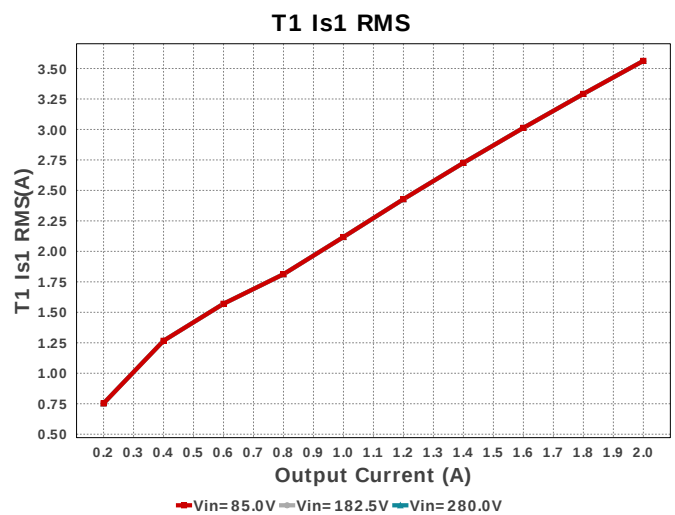
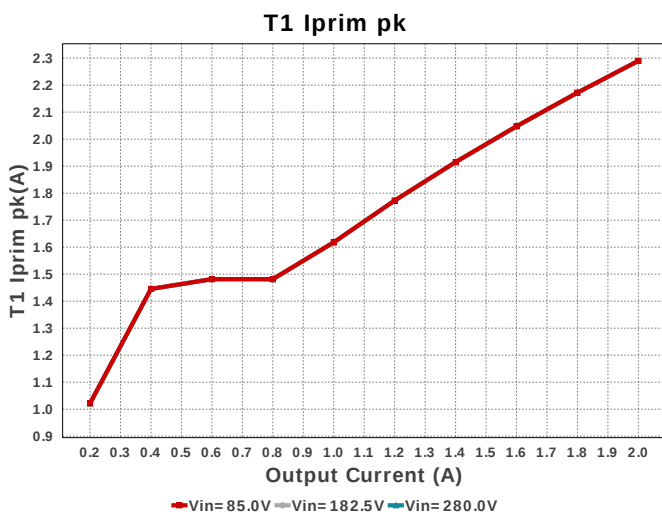
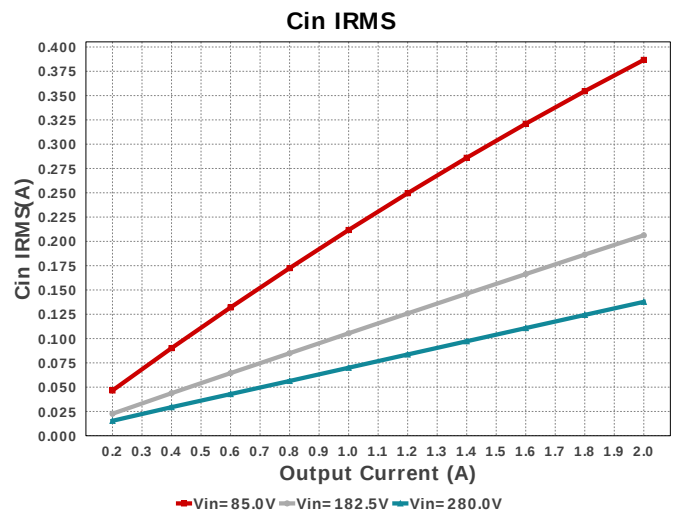
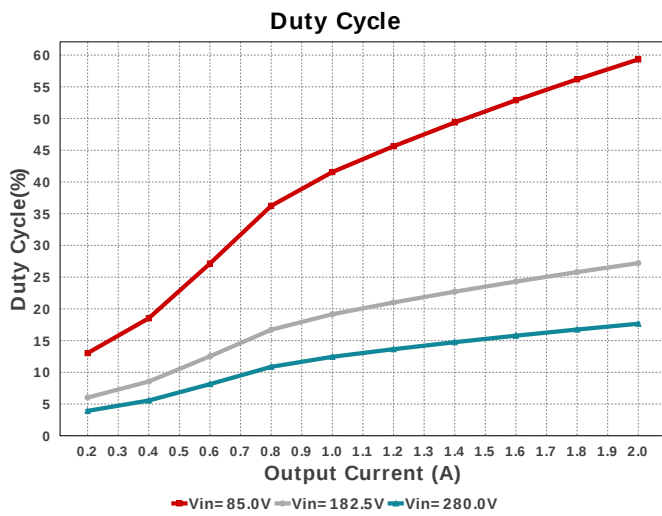
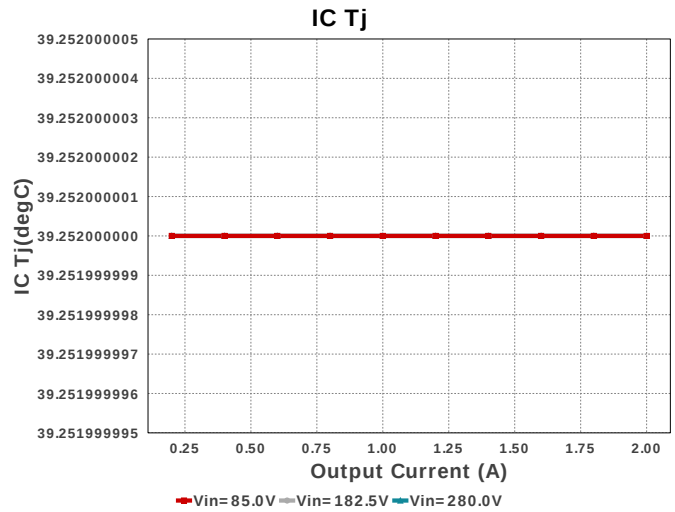
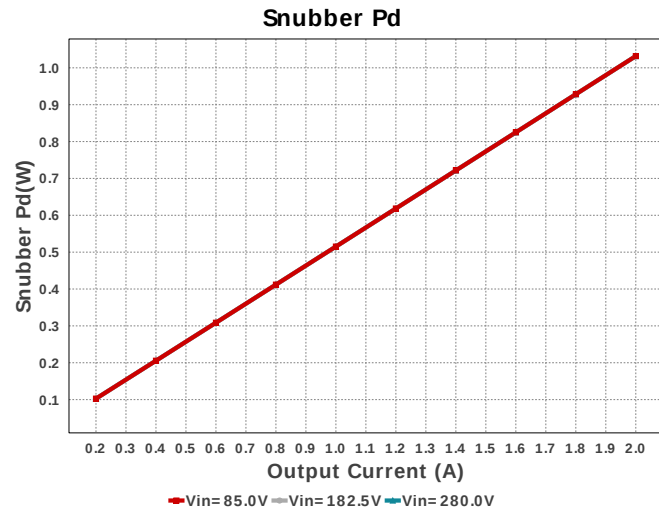
Component Selection Information

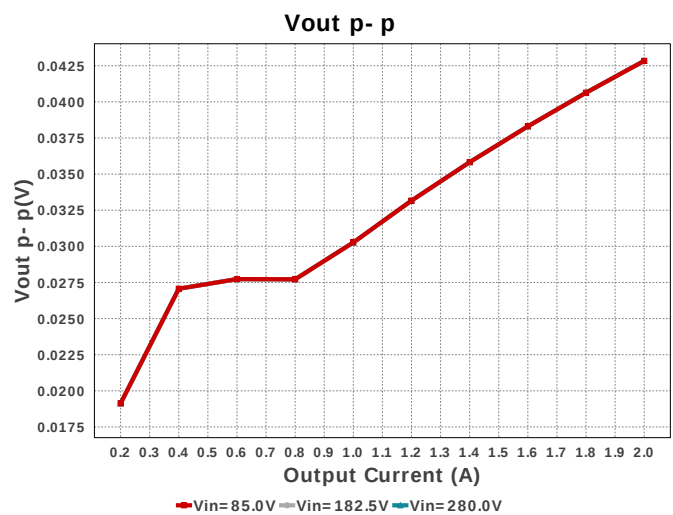
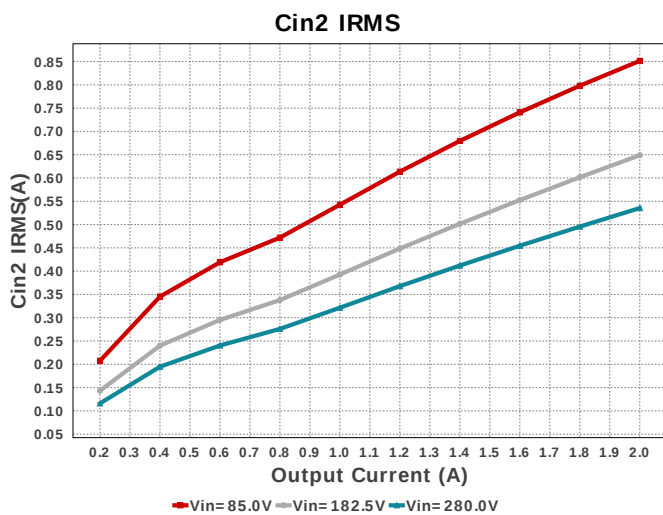
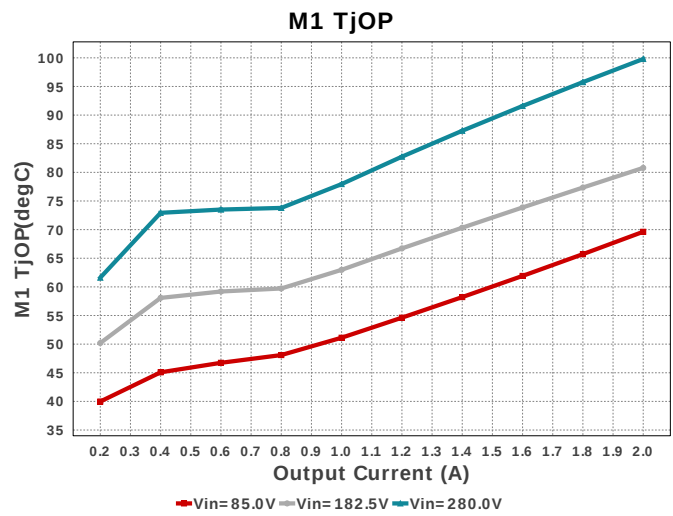
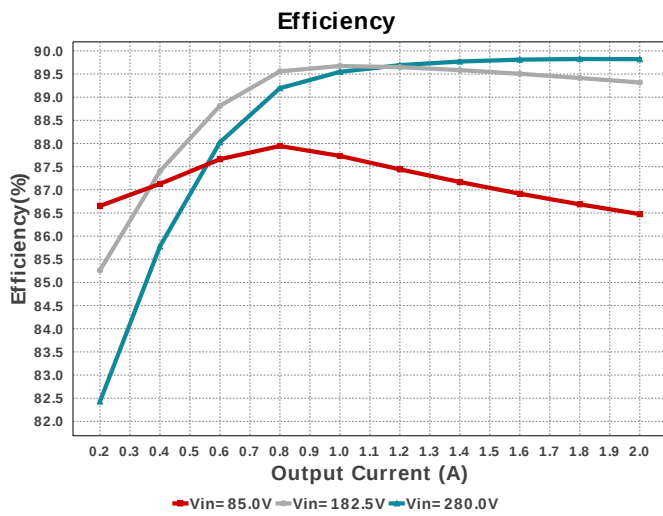
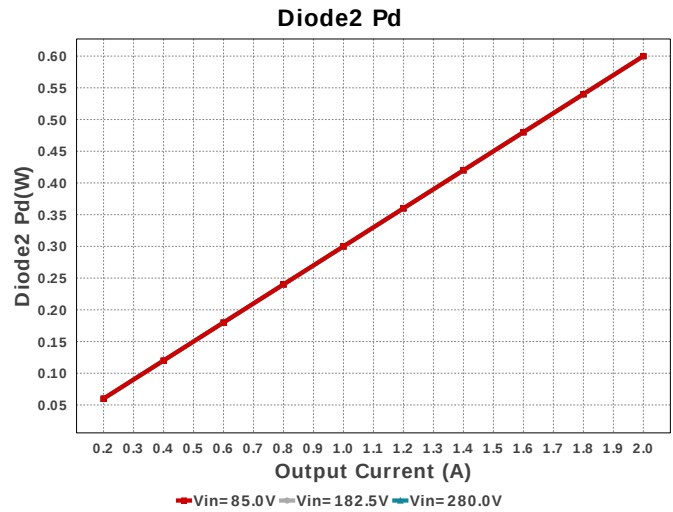
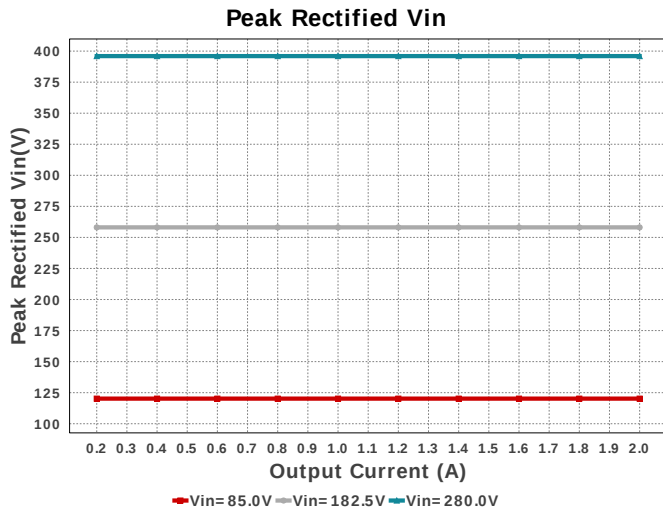
Click on the transformer symbol in the schematic and select "Explore Transformer Core/Bobbin Selection" to design using specific transformer cores and bobbin.

Electrical BOM

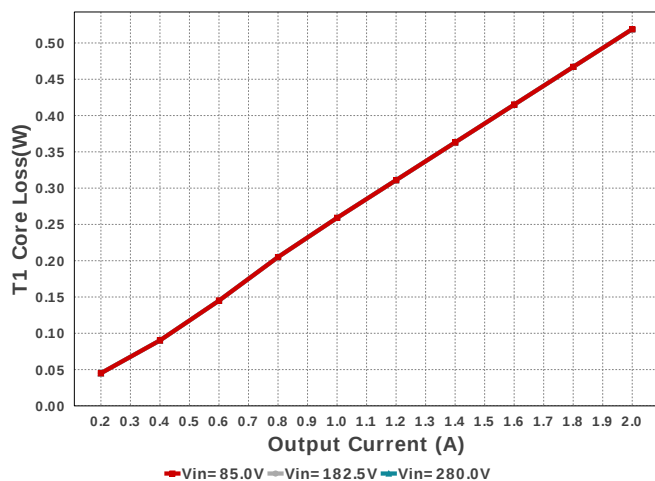
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cdd	TDK	C2012X5R1V156M125AC Series= X5R	Cap= 15.0 uF ESR= 1.669 mOhm VDC= 35.0 V IRMS= 5.0498 A	1	\$0.21	0805 7 mm ²
Cin	CUSTOM	CUSTOM Series= ?	Cap= 22.199 uF ESR= 1.02423 Ohm VDC= 419.73 V IRMS= 395.24 mA	1	NA	CUSTOM 0 mm ²
Cin2	Nichicon	LGU2W470MELY Series= GU	Cap= 47.0 uF ESR= 5.65 Ohm VDC= 450.0 V IRMS= 390.0 mA	2	\$1.20	CAPPRD1000W150D2000H2500 484 mm ²
Cout	Panasonic	35SEPF120M Series= SEPF	Cap= 120.0 uF ESR= 18.0 mOhm VDC= 35.0 V IRMS= 4.4 A	4	\$0.69	SEPF_F13 144 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
D1	Microsemi	UFS180JE3/TR13	VF@Io= 1.2 V VRRM= 800.0 V	1	\$0.73	 DO-214BA 42 mm ²
D2	CUSTOM	CUSTOM	VF@Io= 300.0 mV VRRM= 119.007 V	1	NA	CUSTOM 0 mm ²
D3	SMC Diode Solutions	SK220ATR	VF@Io= 900.0 mV VRRM= 200.0 V	1	\$0.04	 SMA 37 mm ²
D6	Diodes Inc.	1N5711WS-7-F	VF@Io= 800.0 mV VRRM= 70.0 V	1	\$0.09	 SOD-323 9 mm ²
Dac	Vishay-Semiconductor	GBU4K-E3/45	VF@Io= 1.0 V VRRM= 800.0 V	1	\$0.68	 GBU 131 mm ²
Dz1	Diodes Inc.	SMBJ150A-13-F	Zener	1	\$0.09	 SMB 44 mm ²
L1	Coilcraft	MSS1210-473MEB	L= 47.0 µH 48.0 mOhm	1	\$0.81	 MSS1210 204 mm ²
M1	STMicroelectronics	STD13NM60ND	VdsMax= 600.0 V IdsMax= 11.0 Amps	1	\$1.72	 DPAK 102 mm ²
R1	Panasonic	ERJ-8ENF2492V Series= ERJ-8E	Res= 24.9 kOhm Power= 250.0 mW Tolerance= 1.0%	1	\$0.01	 1206 11 mm ²
R2	Vishay-Dale	CMF5035K700FHEB Series= CMF50	Res= 35.7 kOhm Power= 250.0 mW Tolerance= 1.0%	1	\$0.20	 CMF50 46 mm ²
Rbld	Vishay-Dale	CRCW040221K0FKED Series= CRCW..e3	Res= 21.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rcs	Rohm	MCR25JZHFLR270 Series= MCR25	Res= 270.0 mOhm Power= 500.0 mW Tolerance= 1.0%	1	\$0.03	 1210 15 mm ²
Rhv1	Vishay-Dale	CRCW2010100KJNEF Series= CRCW..e3	Res= 100.0 kOhm Power= 750.0 mW Tolerance= 5.0%	1	\$0.03	 2010 32 mm ²
Rp	Yageo	RC0603FR-073K9L Series= ?	Res= 3.9 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm ²
Rprog	Vishay-Dale	CRCW040247K5FKED Series= CRCW..e3	Res= 47.5 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
T1	Core=TDK , CoilFormer=TDK	Core=B66423G0000X187 , CoilFormer=B66424W1012D001	Lp= 328.0 µH Turns Ratio(Nas)= 6:11 Turns Ratio(Nps)= 47:11 Npri= 47.0 Naux= 6.0 Nsec= 11.0	1	\$0.67	 TDK_B66305 1056 mm ²
U1	Texas Instruments	UCC28634DR	Switcher	1	\$0.68	 R-PDSO-G7 55 mm ²

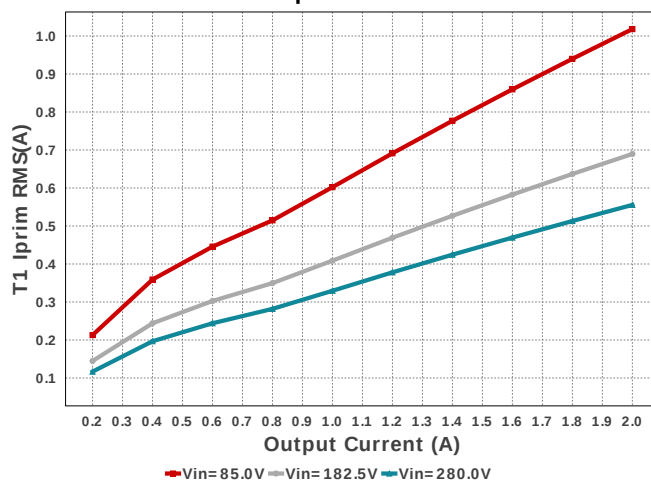




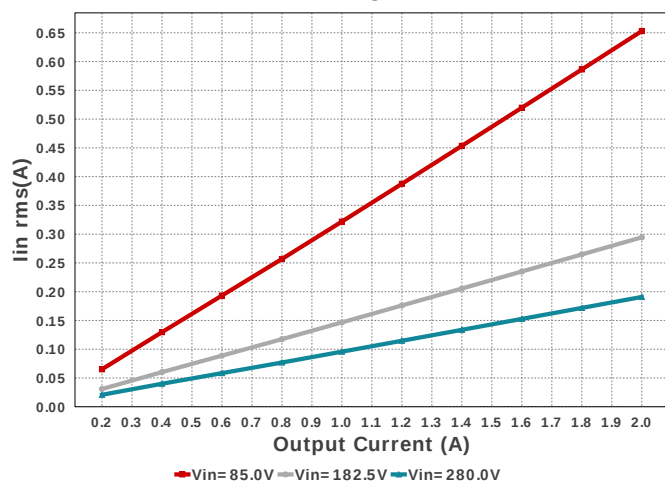
T1 Core Loss



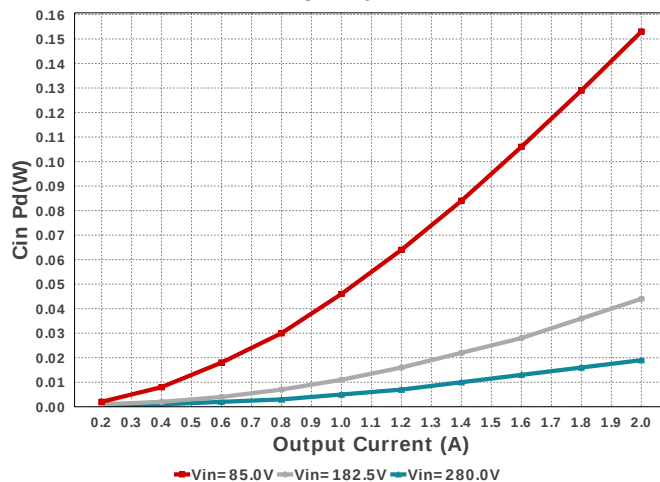
T1 Iprim RMS



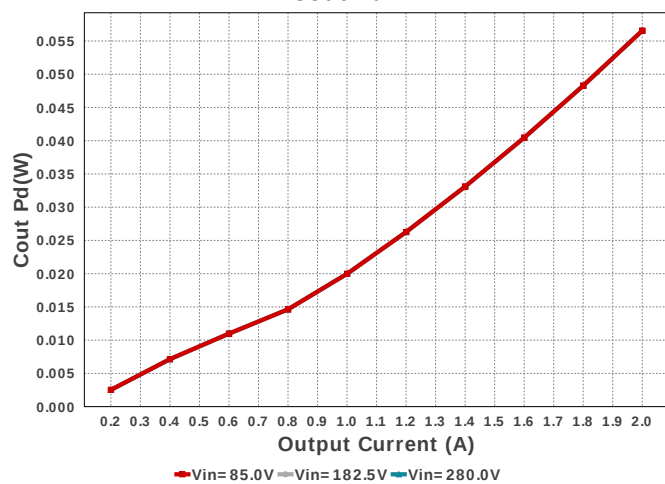
Iin rms



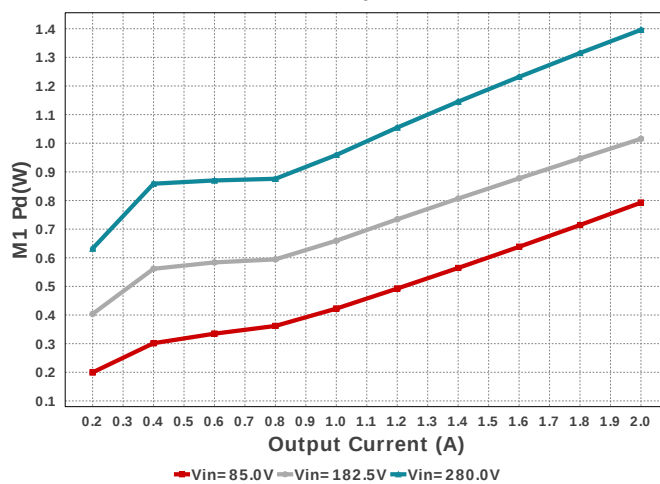
Cin Pd

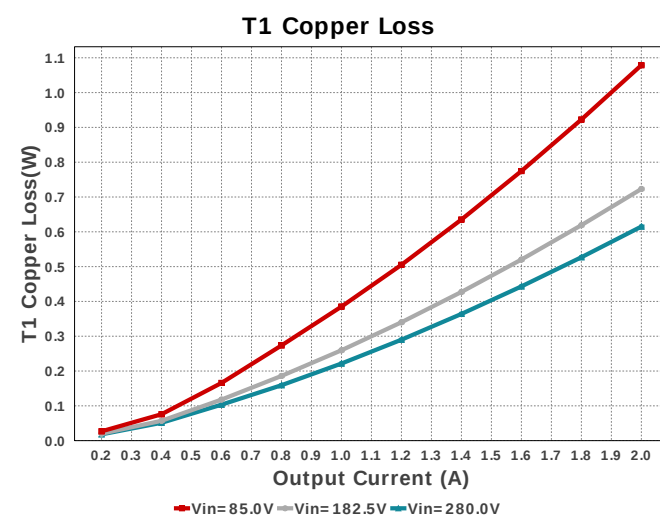
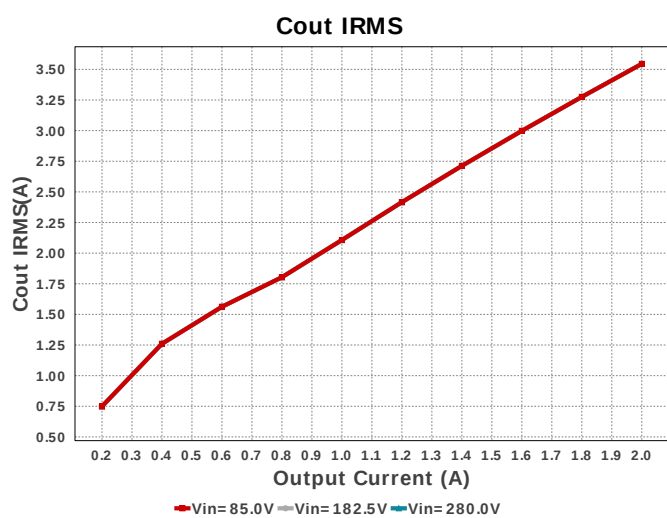
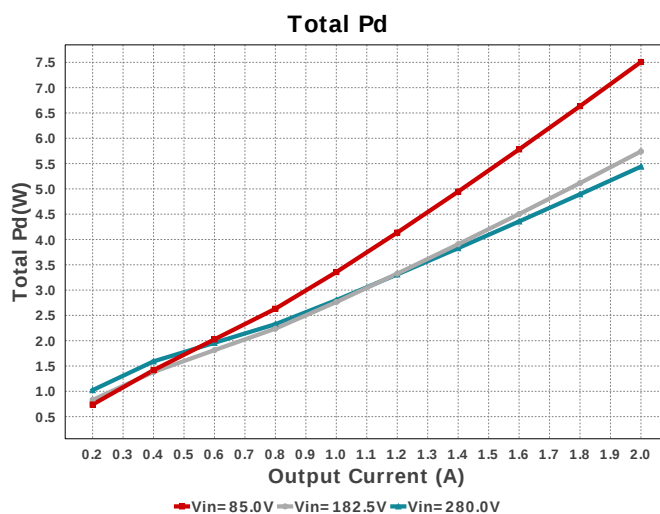
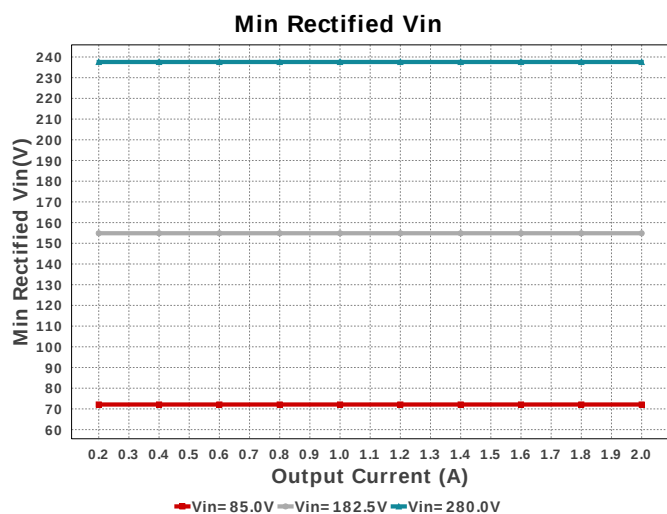
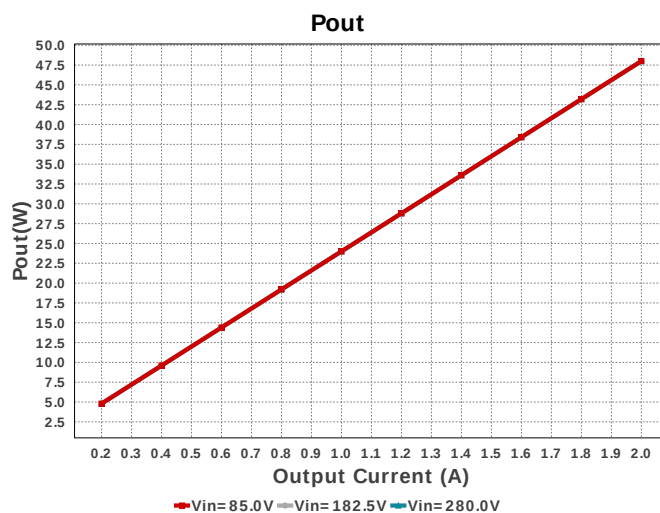
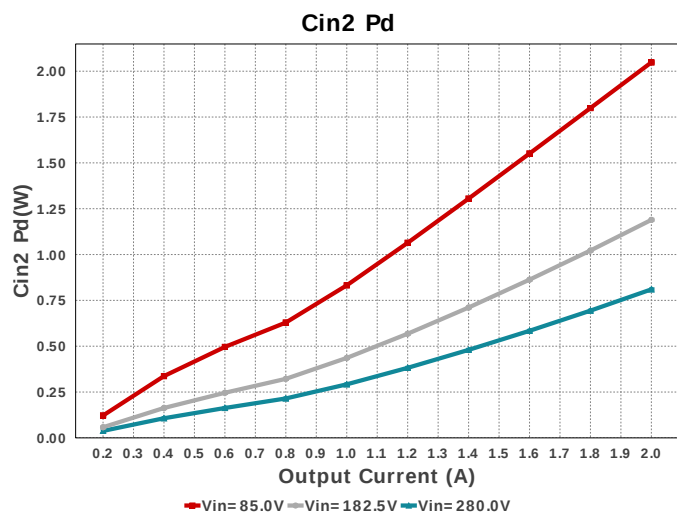


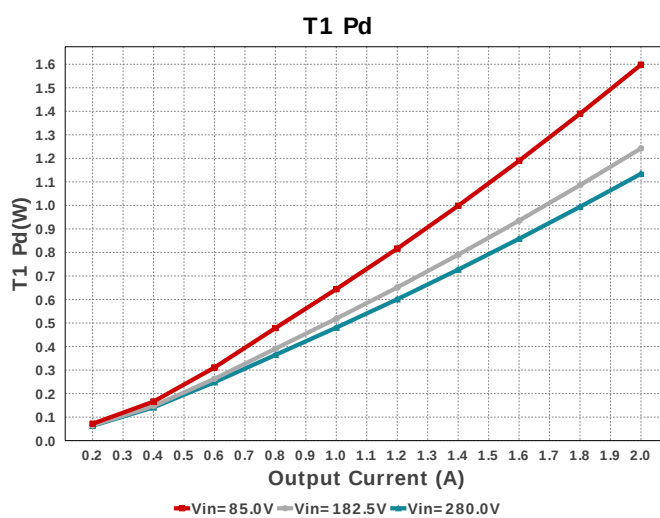
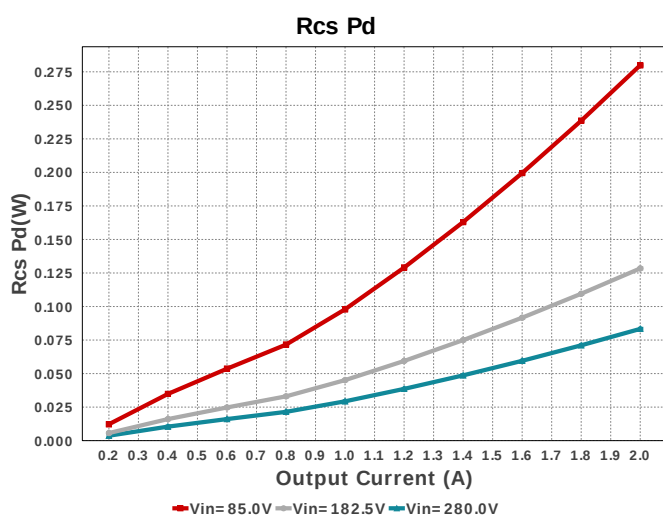
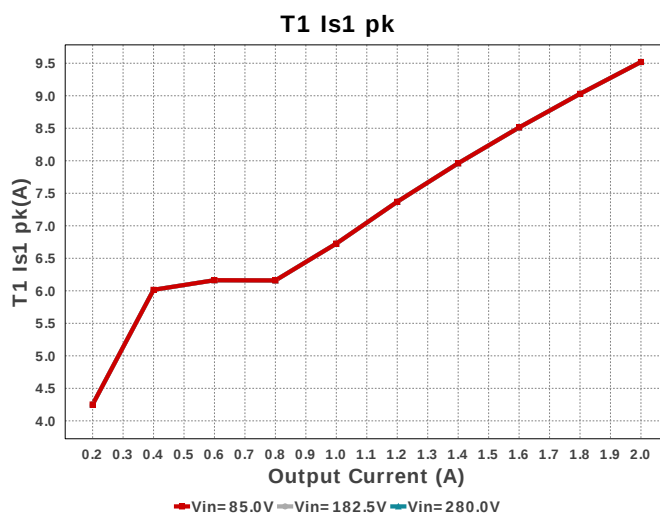
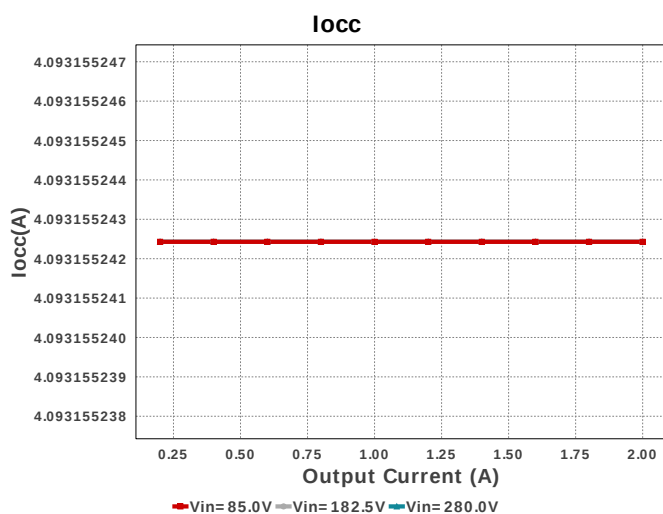
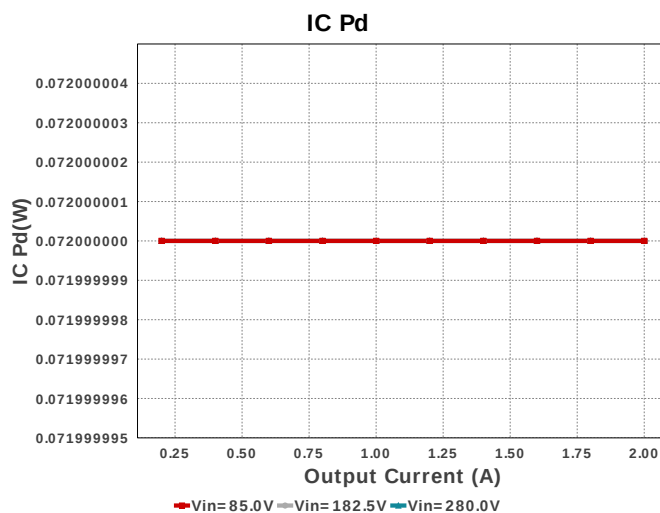
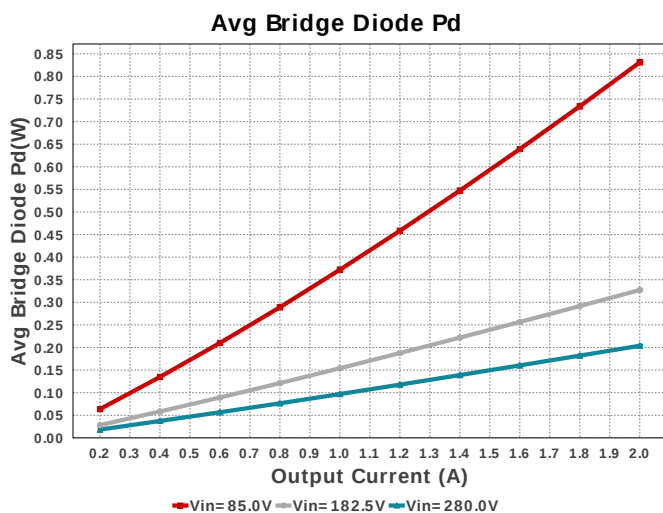
Cout Pd



M1 Pd







Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	389.109 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	155.0 mW	Capacitor	Input capacitor power dissipation
3.	Cin2 IRMS	852.63 mA	Capacitor	Input Capacitor Cin2 RMS Ripple Current
4.	Cin2 Pd	2.054 W	Capacitor	Average Power Dissipation in the Input Capacitor Cin2
5.	Cout IRMS	3.545 A	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	56.551 mW	Capacitor	Output capacitor power dissipation
7.	Avg Bridge Diode Pd	842.73 mW	Diode	Average Power Dissipation in the Bridge Diode over the AC Line Period
8.	Diode2 Pd	600.0 mW	Diode	Diode2 power dissipation
9.	IC Pd	72.0 mW	IC	IC power dissipation
10.	IC Tj	39.252 degC	IC	IC junction temperature
11.	ICThetaJA	128.5 degC/W	IC	IC junction-to-ambient thermal resistance

#	Name	Value	Category	Description
12.	M1 Pd	1.244 W	Mosfet	M1 MOSFET total power dissipation
13.	M1 TjOP	92.216 degC	Mosfet	M1 MOSFET junction temperature
14.	Avg Bridge Diode Pd	842.73 mW	Power	Average Power Dissipation in the Bridge Diode over the AC Line Period
15.	Cin Pd	155.0 mW	Power	Input capacitor power dissipation
16.	Cin2 Pd	2.054 W	Power	Average Power Dissipation in the Input Capacitor Cin2
17.	Cout Pd	56.551 mW	Power	Output capacitor power dissipation
18.	Diode2 Pd	600.0 mW	Power	Diode2 power dissipation
19.	IC Pd	72.0 mW	Power	IC power dissipation
20.	M1 Pd	1.244 W	Power	M1 MOSFET total power dissipation
21.	Rcs Pd	279.92 mW	Power	Current Limit Sense Resistor Power Dissipation
22.	Snubber Pd	1.032 W	Power	Snubber Power Dissipation
23.	T1 Copper Loss	968.06 mW	Power	Transformer Copper Loss Power Dissipation
24.	T1 Core Loss	556.0 mW	Power	Transformer Core Loss Power Dissipation
25.	T1 Pd	1.524 W	Power	Estimated Losses in Transformer
26.	Total Pd	7.905 W	Power	Total Power Dissipation
27.	Rcs Pd	279.92 mW	Resistor	Current Limit Sense Resistor Power Dissipation
28.	BOM Count	25	System Information	Total Design BOM count
29.	Duty Cycle	59.309 %	System Information	Duty cycle
30.	Efficiency	85.86 %	System Information	Steady state efficiency
31.	FootPrint	3.478 k mm ²	System Information	Total Foot Print Area of BOM components
32.	Frequency	60.0 kHz	System Information	Switching frequency
33.	Iin rms	657.7 mA	System Information	RMS Input Current
34.	Iocc	4.25 A	System Information	Constant Current Limit
35.	Iout	2.0 A	System Information	Iout operating point
36.	Min Rectified Vin	72.124 V	System Information	Minimum voltage seen at rectified input
37.	Mode	DCM	System Information	Conduction Mode
38.	Peak Rectified Vin	120.207 V	System Information	Peak voltage seen at rectified input
39.	Pout	48.0 W	System Information	Total output power
40.	Total BOM	NA	System Information	Total BOM Cost
41.	Vin_RMS	85.0 V	System Information	Vin operating point
42.	Vout	24.0 V	System Information	Operational Output Voltage
43.	Vout p-p	42.842 mV	System Information	Peak-to-peak output ripple voltage
44.	T1 Copper Loss	968.06 mW	Transformer	Transformer Copper Loss Power Dissipation
45.	T1 Core Loss	556.0 mW	Transformer	Transformer Core Loss Power Dissipation
46.	T1 Iprim RMS	1.018 A	Transformer	Transformer Primary RMS Current
47.	T1 Iprim pk	2.29 A	Transformer	Transformer Primary Peak Current
48.	T1 Is1 RMS	3.563 A	Transformer	Transformer Secondary1 RMS Current
49.	T1 Is1 pk	9.52 A	Transformer	Transformer Secondary1 Peak Current
50.	T1 Pd	1.524 W	Transformer	Estimated Losses in Transformer

Design Inputs

Name	Value	Description
Iout	2.0	Maximum Output Current
VinMax	280.0	Maximum input voltage
VinMin	85.0	Minimum input voltage
Vout	24.0	Output Voltage
acFrequency	60.0	AC Frequency
base_pn	UCC28634	Base Product Number
source	AC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

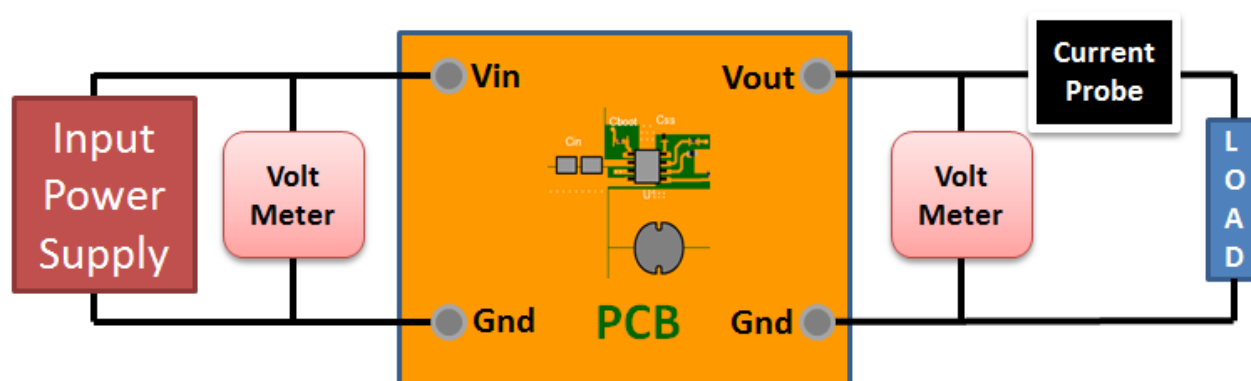
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 85.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



WEBENCH® Transformer Report

#	Name	Value
1.	Core Part Number	B66423G0000X187
2.	Core Manufacturer	TDK
3.	Coil Former Part Number	B66424W1012D001
4.	Coil Former Manufacturer	TDK

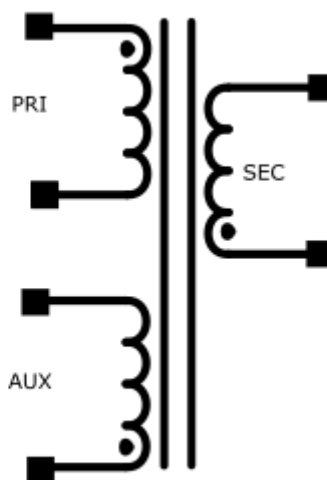
Transformer Electrical Diagram

Primary

Turns	47.0
AWG	24.0
Layers	3.0
Strands	2.0
Insulation Type	Heavy Insulated Magnet Wire

Auxiliary

Turns	6.0
AWG	28.0
Layers	1.0
Strands	4.0
Insulation Type	Heavy Insulated Magnet Wire



Secondary

Turns	11.0
AWG	24.0
Layers	1.0
Strands	2.0
Insulation Type	Triple Insulated

Transformer Construction Diagram

TRANSFORMER WINDING DIAGRAM – COMING SOON

Winding Instruction

Winding	AWG	Turns	Winding Orientation
Primary First 2/3.0	24.0	32	Clockwise
Triple Insulated Secondary	24.0	11.0	Counter Clockwise
Auxiliary	28.0	6.0	Counter Clockwise
Primary Second 1/3.0	24.0	15	Clockwise

Transformer Parameters

#	Name	Value
1.	Lpri	3.28E-4H
2.	Inductance Factor(Al)	149.0nH
3.	Npri	47.0
4.	Nsec	11.0
5.	Naux	6.0
6.	Core Type	EFD30/15/9
7.	Core Material	N87
8.	Bmax	0.24T
9.	Switching Frequency	60.00kHz
10.	DMax	0.58
11.	Ipk(Primary)	2.37A
12.	Irms(Primary)	1.04A

#	Name	Value
13.	Ipk(Secondary)	10.1A
14.	Irms(Secondary)	3.81A

Design Assistance

1. Application Hints High Power Operation The UCC28630 allows a peak power delivery up to 200% the nominal rating with only a modest increase in peak current. The combination of up to 2x frequency increase and 1.25x peak current increase in CCM allows up to 2x peak power delivery capability for a given transformer size. Rbld Rbld is used to set a minimum load for the circuit, so that in standby the output voltage does not float up. The value chosen by WEBENCH should be a good starting point but may need to be adjusted to achieve minimum power dissipation at standby as well. Active X-Cap Discharge The X-capacitor discharge function discharges the X-capacitor to the SELV 60V level in 1 sec. When adjusting the components for the design, ensure that the bulk capacitance value is not too large for the power level desired, which ensures that the bulk capacitor discharge rate is fast enough to discharge the X-capacitor to meet the 1-second discharge target. The VSENSE terminal In order to protect the VSENSE terminal from excessive negative current, an additional series limiting resistor and clamping diode can be added on the VSENSE terminal. The DRV pull up diode can be combined with the clamping diode in a single package common-cathode diode to reduce the component count of the circuit (see Figure 24 in the datasheet for illustration). Magnetic Sense Resistor Network When adjusting components for the design, check that the equivalent Thevenin resistance (Rth) of the R1/R2 falls within the required range of 10kOhm and 20kOhm. If the Rth is outside of this range, it triggers the VSENSE terminal open or short terminal check at start-up. Peak Current Mode Control and the CS Terminal Depending on the PCB layout, an additional RC filter may be required on the CS terminal, as show in Figure 30 of the datasheet. The capacitor, Ccs, should be positioned as close as possible to terminals 3 and 4 and tracked directly to the terminals. Rcs2 should also be located close to terminal 3 to minimize noise, and should not exceed 20kOhms since larger values could be detected as a possible open circuit on the CS terminal during the start-up terminal checks. The time constant for this RC filter should no be excessive so that the filter does not reduce the measured peak current. Typical time values would fall between 100ns and 200ns. Primary-Side Overload Timer An internal overload timer tracks the power stage thermal stress and protects the power stage against output overload. The overload timer trip level and time constant are both selectable from a defined list of combinations (See Table 1 in datasheet for combinations), and is set using a pull-down resistance, Rprog, on the DRV terminal. The values of the Rprog resistor that corresponds to specific trip levels and time constants can also be seen in Table 1 in the datasheet. Please see the datasheet for further design guidance and recommendations. <http://www.ti.com/lit/ds/symlink/ucc28630.pdf>

2. Master key : A98914AE06870871[v1]

3. **UCC28634** Product Folder : <http://www.ti.com/product/UCC28634> : contains the data sheet and other resources.

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